

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S17 4	32787	(molding moulding) near1 apparatus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/16 14:22
S17 5	304614	(chip die (semiconductor near1 (element device))) with (carrier substrate pcb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/16 14:35
S17 6	160	S174 with S175	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/16 14:37
S17 7	46	S176 with cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/16 14:38
S17 8	0	S177 and (second near2 (seal sealing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/16 14:39
S17 9	0	S176 same (second near1 (seal sealing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/16 14:47

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S180	32787	(molding moulding) near1 apparatus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/16 15:10
S181	160	S180 with (chip die (semiconductor near1 (element device))) with (carrier substrate pcb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/16 15:12
S182	10	S181 with (seal sealing rubber elastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/16 15:14
S183	16	S181 same (seal sealing rubber elastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/16 15:40
S184	6	S183 not: S182	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/16 15:39